T Number	ui+e l	Search Text	DB	Time stamp
L Number		257/685	USPAT;	2003/05/22 11:17
	920	2317 003	US-PGPUB;	
			EPO; JPO;	1
1			DERWENT	
-	2074	257/686	USPAT;	2003/05/22 11:17
ļ			US-PGPUB;	
1 1			EPO; JPO;	
	İ		DERWENT	2003/05/22 13:24
-	4631	257/666	USPAT; US-PGPUB;	2003/05/22 13:24
			EPO; JPO;	
			DERWENT	
	2025	257/600	USPAT;	2003/05/22 11:17
-	2235	257/690	US-PGPUB;	2000, 50, 50
]			EPO; JPO;	
			DERWENT	
1_	2469	257/692	USPAT;	2003/05/22 11:17
_	2105	2017 032	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	1660	257/701	USPAT;	2003/05/22 11:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	2003/05/22 11:17
-	4044	257/787	USPAT;	2003/03/22 11:17
			US-PGPUB; EPO; JPO;	
			DERWENT	
	10045	257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 11:18
-	13245	257/685 257/686 257/686 257/690 257/692	US-PGPUB;	2003/03/22 11:10
		257/701 257/767	EPO; JPO;	
			DERWENT	
	3253	(257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 12:19
-	3233	257/701 257/787) and lead and (chip die	US-PGPUB;	
		IC (integrated near circuit)) and	EPO; JPO;	<u> </u>
		(encapsulant encapsulating encapsulate	DERWENT	
		mold)		
_	965	((257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 11:22
		257/701 257/787) and lead and (chip die	US-PGPUB;	
		IC (integrated near circuit)) and	EPO; JPO; DERWENT	
		(encapsulant encapsulating encapsulate	DEKMENI	
		mold)) and ((I/O bond input/output) near		
	0.7	pad) ((257/685 257/686 257/666 257/690 257/692	USPAT;	2003/05/22 13:22
-	27	257/701 257/787) and lead and (chip die	US-PGPUB;	2000, 20, 22
		IC (integrated near circuit)) and	EPO; JPO;	
		(encapsulant encapsulating encapsulate	DERWENT	
		mold)) and (lead near recess\$3)		
_	26		USPAT;	2003/05/22 13:22
			US-PGPUB;	
			EPO; JPO;	
İ			DERWENT	2002/05/22 12:22
-	9	(257/666 and (lead near recess\$3)) not	USPAT;	2003/05/22 13:22
	1	(((257/685 257/686 257/666 257/690 257/692	US-PGPUB; EPO; JPO;	
	1	257/701 257/787) and lead and (chip die	DERWENT	
		IC (integrated near circuit)) and (encapsulant encapsulating encapsulate	DEKMENT	
		mold)) and (lead near recess\$3))		
	1450	257/666 and chip and (encapsulant	USPAT;	2003/05/22 15:04
_	1450	encapsulating encapsulate mold)	US-PGPUB;	
		Charbaracting charbaratan mana,	EPO; JPO;	
			DERWENT	
_	1019	(257/666 and chip and (encapsulant	USPAT;	2003/05/22 15:04
		encapsulating encapsulate mold)) not	US-PGPUB;	
		(((257/685 257/686 257/666 257/690 257/692	EPO; JPO;	
1		257/701 257/787) and lead and (chip die	DERWENT	
		IC (integrated near circuit)) and		
		(encapsulant encapsulating encapsulate		
		mold)) and ((I/O bond input/output) near		
		pad))		

r	T ==:	1		
_	781	((257/666 and chip and (encapsulant	USPAT;	2003/05/22 15:05
		encapsulating encapsulate mold)) not	US-PGPUB;	
	i	(((257/685 257/686 257/666 257/690 257/692	EPO; JPO;	
		257/701 257/787) and lead and (chip die	DERWENT	
		IC (integrated near circuit)) and (encapsulant encapsulating encapsulate		
		mold)) and ((I/O bond input/output) near		
		pad))) and pad		
_	294		USPAT;	2003/06/05 15:26
	233	near lead) and chip and ((I/O	US-PGPUB;	2003/00/03 13:20
		input/output) near pad)	EPO; JPO;	
		input, suspend, mour puu,	DERWENT	
-	1872	lead and chip and ((I/O input/output) near	USPAT;	2003/06/05 13:38
		pad)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	668	(lead and chip and ((I/O input/output)	USPAT;	2003/06/05 15:28
		near pad)) and 257/\$6.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	505	((=)	USPAT;	2003/06/05 13:39
ļ		near pad)) and 257/\$6.ccls.) not (((metal	US-PGPUB;	
		conductive conducting conductor) near	EPO; JPO;	
		<pre>lead) and chip and ((I/O input/output) near pad))</pre>	DERWENT	
_	294		USPAT;	2003/06/05 15:28
-	234	near lead) and chip and ((I/O input/output	US-PGPUB;	2003/06/03 15:28
		bong) near pad)	EPO; JPO;	
		bong, near paa,	DERWENT	
-	1346	((metal conductive conducting conductor)	USPAT;	2003/06/05 15:28
		near lead) and chip and ((I/O input/output	US-PGPUB;	,,
		bond) near pad)	EPO; JPO;	-
	ļ	-	DERWENT	
-	1052	(((metal conductive conducting conductor)	USPAT;	2003/06/05 15:28
		near lead) and chip and ((I/O input/output	US-PGPUB;	
		bond) near pad)) not (((metal conductive	EPO; JPO;	
		conducting conductor) near lead) and chip	DERWENT	
		and ((I/O input/output) near pad))		
-	516	((((· · · · · · · · · · · · · · ·	USPAT;	2003/06/05 15:29
		near lead) and chip and ((I/O input/output	US-PGPUB;	
		bond) near pad)) not (((metal conductive conducting conductor) near lead) and chip	EPO; JPO;	
		and ((I/O input/output) near pad))) and	DERWENT	
		257/\$6.ccls.		
_	516		USPAT;	2003/06/05 15:29
	1	conductor) near lead) and chip and ((I/O	US-PGPUB;	2003/00/03 13:23
		input/output bond) near pad)) not ((metal	EPO; JPO;	
		conductive conducting conductor) near	DERWENT	
		lead) and chip and ((I/O input/output)		
		near pad))) and 257/\$6.ccls.) not (((lead		
		and chip and ((I/O input/output) near		
		pad)) and 257/\$6.ccls.) not (((metal		
		conductive conducting conductor) near		
		lead) and chip and ((I/O input/output)		
		near pad)))		

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